

~~Claim 11, line 22, amend " ." to ---.~~

~~Claim 11, line 29, amend ";" to ---.~~

~~Claim 12, line 15, delete "first".~~

~~Claim 12, line 28, amend ";" to ---.~~

Please cancel claims 13 and 14 without prejudice.

Please add new claims 32-45 as follows:

<sup>27</sup> 32. (New) An illumination optical apparatus

<sup>24</sup> according to claim <sup>21</sup>, further comprising: a conversion member for converting plural light-source-images formed by said optical integrator into a light-source-image having a ring shape or a light-source-image of which center is shifted from an optical axis of optical system of said illumination optical apparatus.

<sup>31</sup> 33. (New) An illumination optical apparatus

<sup>29</sup> according to claim <sup>22</sup>, further comprising: a conversion member for converting plural light-source-images formed by said optical integrator into a light-source-image having a ring shape or a light-source-image of which center is shifted from an optical axis of optical system of said illumination optical apparatus.

<sup>39</sup> 34. (New) An illumination optical apparatus

<sup>33</sup> according to claim <sup>23</sup>, further comprising: a conversion member for converting plural light-source-images formed by said optical integrator into a light-source-image having a ring shape or a light-source-image of which center is shifted from

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an optical axis of optical system of said illumination optical apparatus.

42  
35. (New) An illumination optical apparatus according to claim 24, further comprising: a conversion member for converting plural light-source-images formed by said optical integrator into a light-source-image having a ring shape or a light-source-image of which center is shifted from an optical axis of optical system of said illumination optical apparatus.

7  
36. (New) A method of fabricating a semiconductor device using an illumination optical apparatus according to claim 1, said method comprising the steps of:

guiding a light from said illumination apparatus to a mask on which a predetermined circuit pattern is formed and illuminating the pattern; and

with moving said mask and photo-sensitive substrate in predetermined directions respectively, projecting said pattern of the mask on the sensitive substrate.

11  
37. (New) A method of fabricating a semiconductor device using an illumination optical apparatus according to claim 2, said method comprising the steps of:

guiding a light from said illumination apparatus to a mask on which a predetermined circuit pattern is formed and illuminating the pattern; and

4

with moving said mask and photo-sensitive substrate in predetermined directions respectively, projecting said pattern of the mask on the sensitive substrate.

38. (New) A method of fabricating a semiconductor device using an illumination optical apparatus according to claim 4, said method comprising the steps of:

guiding a light from said illumination apparatus to a mask on which a predetermined circuit pattern is formed and illuminating the pattern; and

with moving said mask and photo-sensitive substrate in predetermined directions respectively, projecting said pattern of the mask on the sensitive substrate.

18  
39. (New) A method of fabricating a semiconductor device using a scanning exposure apparatus according to claim 17, said method comprising the steps of:

guiding a light from said condenser optical system to a said reticle and illuminating said reticle; and

with moving said reticle stage and said wafer stage in predetermined directions respectively, projecting a pattern of said reticle on said wafer to perform the exposure.

22  
40. (New) A method of fabricating a semiconductor device using a scanning exposure apparatus according to claim 19, said method comprising the steps of:

guiding a light from said condenser optical system to a said reticle and illuminating said reticle; and

Cont 03B /

with moving said reticle stage and said wafer stage in predetermined directions respectively, projecting a pattern of said reticle on said wafer to perform the exposure.

28

41. (New) A method of fabricating a semiconductor device using an illumination optical apparatus according to claim 21, <sup>24</sup> said method comprising the steps of:

guiding a light from said illumination apparatus to a mask on which a predetermined circuit pattern is formed and illuminating the pattern; and

with moving said mask and photo-sensitive substrate in predetermined directions respectively, projecting said pattern of the mask on the sensitive substrate.

32

42. (New) A method of fabricating a semiconductor device using an illumination optical apparatus according to claim 22, <sup>29</sup> said method comprising the steps of:

guiding a light from said illumination apparatus to a mask on which a predetermined circuit pattern is formed and illuminating the pattern; and

with moving said mask and photo-sensitive substrate in predetermined directions respectively, projecting said pattern of the mask on the sensitive substrate.

40

43. (New) A method of fabricating a semiconductor device using a scanning exposure apparatus according to claim 23, <sup>33</sup> said method comprising the steps of:

guiding a light from said condenser optical system to said reticle to illuminate said reticle; and

102